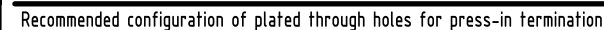


NFF classification	I3, F3
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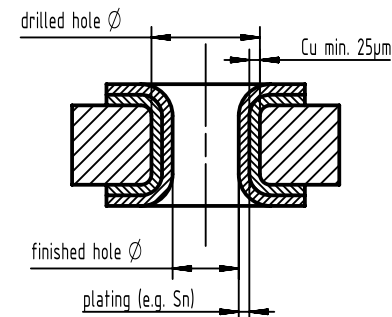
Plating contact zone	acc. to performance level, see table below
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Standard plating options highlighted in *italic*, other plating options are available on request.

Control and test procedures according to DIN IEC 60512-5



In addition to the hot-air-level (HAL), other PCB surfaces are getting more important. Due to their different properties - such as mechanical strength and coefficient of friction - we recommend the following configuration of PCB through holes.



Tin plated PCB (HAL) acc. to EN 60352-5	Drilled hole Ø	1,15±0,025mm
	Sn	max. 15µm
	plated hole Ø	0,94 - 1,09mm
Chemical tin plated PCB	Drilled hole Ø	1,15±0,025mm
	Sn	min. 0,8µm
	plated hole Ø	1,00 - 1,10mm
Gold /Nickel plated PCB	Drilled hole Ø	1,15±0,025mm
	Ni	3 - 7µm
	Au	0,05 - 0,12µm
	plated hole Ø	1,00 - 1,10mm
Silver plated PCB	Drilled hole Ø	1,15±0,025mm
	Ag	0,1 - 0,3µm
	plated hole Ø	1,00 - 1,10mm
Copper plated PCB (OSP)	Drilled hole Ø	1,15±0,025mm
	plated hole Ø	1,00 - 1,10mm

It is highly recommended to use HARTING press-in tools to ensure a reliable press-in process.
Please refer to the catalogue for tools, machines and further information about the press-in process.

THR (Through Hole Reflow) connectors are designed to be used in a reflow oven together with other SMD (Surface Mount Device) components. In this process, called as well „Pin in Hole Intrusive Reflow“, the connectors are inserted into plated through holes in a comparable way to conventional component mounting. All other components can be assembled on the pcb surface.

The length of the connector contacts should be such that they protrude by no more than 1.5 millimetres after insertion to the pcb. Each contact collects solder on its tip as it penetrates the solder paste in the hole. So if the contact is too long, this solder would no longer be able to reflow back into the plated through hole by capillary action during the soldering process, therefore the quality of the soldered connection would suffer as a result.

Before the components are assembled, solder paste must be applied to all the solder pads (for connecting surface-mount components) and the plated through holes.

To ensure that the plated through holes are completely filled, significantly more solder paste must be applied than traditional solder pads on the pcb surface.

There are numerous calculation methods available which are complicated to apply.

The following rule of thumb has proved valuable in practice:

$VPaste = 2(VH - VP)$
in which:
VPaste = Required volume of solder paste
VH = Volume of the plated through hole
VP = Volume of the connector termination in the hole

Comment: the multiplier "2" compensates for solder paste shrinkage during soldering. For this purpose, it was assumed that 50 % of the paste consists of the actual solder, the other 50 % being soldering aids.

Technical drawing of a rectangular part with dimensions and tolerances. The vertical dimension is $0,6^{+0,05}$. The horizontal dimension is $0,6_{-0,025}$. A hatched rectangular area is shown in the top right corner, with dimensions $0,35\text{mm}$ and $0,39\text{mm}$. The formula $A = 0,35\text{mm}^2 - 0,39\text{mm}^2$ is written next to it.



All Dimensions in mm
Original Size DIN A3

Scale
1:1

Free size tol.	
----------------	--

Ref.

Sub.



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Standardisation

HOFFMANN

Date _____

2018-05-15

State

Final Release

Title
DIN Signal male connector straight - THR (CTI>400)

Doc-Key / ECM-Nr.	100571108/UGD/001/C
	500000135180

HARTING Electronics GmbH

D-32339 Espelkamp

Type

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

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